



Product Change Notification

Change Notification #: 114239 - 00

Change Title: Intel® SSD DC P3608 Series (1.6TB, 1/2 Height PCIe 3.0 x8, 20nm, MLC)
Generic Single Pack,
Intel® SSD DC P3608 Series (1.6TB, 1/2 Height PCIe 3.0 x8, 20nm, MLC)
Generic 10 Pack,
Intel® SSD DC P3608 Series (3.2TB, 1/2 Height PCIe 3.0 x8, 20nm, MLC)
Generic Single Pack,
Intel® SSD DC P3608 Series (3.2TB, 1/2 Height PCIe 3.0 x8, 20nm, MLC)
Generic 10 Pack,
Intel® SSD DC P3608 Series (4.0TB, 1/2 Height PCIe 3.0 x8, 20nm, MLC)
Generic Single Pack,
Intel® SSD DC P3608 Series (4.0TB, 1/2 Height PCIe 3.0 x8, 20nm, MLC)
Generic 10 Pack, PCN 114239-00, Label, Label Update

Date of Publication: December 08, 2015

Key Characteristics of the Change:

Label

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Dec 23, 2015
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Description of Change to the Customer:

The Intel® SSD DC P3608 Series SKUs listed in the Products Affected table below will have the following Australia Regulatory Mark Change:









The Australian Communications and Media Authority's (ACMA) labeling arrangements to reflect

- Regulatory compliance changed on 1 March 2013, to be phased in over a three-year transition period. Products shipping March 1, 2016 need to be labeled with the "RCM" mark.
- Per ACMA requirements, Intel will be changing the C-Tick regulatory mark on all products to the "RCM" mark.









Australia Label:



Before Disti label

SSDXXXXXXXXXXXX	QTY: 10	Pb-free 2LI
		PACKED BY: XXXXXX
MM #: XXXXXX	MADE IN CHINA WITH PARTIAL FOREIGN CONTENT	
	Intel Corporation Attn: Corporate Quality 2200 Mission College Blvd. Santa Clara, CA 95054-1549, USA	
PACK DATE: XX XXX XX	 7 3585812345 7	
CARTON #: XXXXXXXXXXX	PCIe Card (PCIe 卡)	
	상호: INTEL CORPORATION	
VERSION #: XXXXXX-XXX	제조사: INTEL CORPORATION	
	Compliance Model Number: SSDPE2ME016T4S	
BATCH #: XXXXXXXXXXX	(型号) (型號)	
		
	MSIP-REM-CPU-SSDPCIA	

After Disti label

SSDXXXXXXXXXXXX	QTY: 10	Pb-free 2LI
		PACKED BY: XXXXXX
MM #: XXXXXX	MADE IN CHINA WITH PARTIAL FOREIGN CONTENT	
	Intel Corporation Attn: Corporate Quality 2200 Mission College Blvd. Santa Clara, CA 95054-1549, USA	
PACK DATE: XX XXX XX	 7 3585812345 7	
CARTON #: XXXXXXXXXXX	PCIe Card (PCIe 卡)	
	상호: INTEL CORPORATION	
VERSION #: XXXXXX-XXX	제조사: INTEL CORPORATION	
	Compliance Model Number: SSDPE2ME016T4S	
BATCH #: XXXXXXXXXXX	(型号) (型號)	
		
	MSIP-REM-CPU-SSDPCIA	

Customer Impact of Change and Recommended Action:

There is no change to the form, fit, or function of the product. The change is only to the Australia Regulatory Mark on the label.

Customers should be aware of the changes to the label and take appropriate actions to accommodate the changes and avoid impact to their process.

Milestone dates are estimates and subject to change based on business and operational conditions.

Please contact your local Intel Field Sales Representative if you have any further questions about these changes.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Pre Change SA	Post Change TA	Post Change SA
SSDPECME016T401	943186	H76846-102	H65413-102	H76846-103	H65413-103
SSDPECME032T401	943187	H76847-102	H65415-102	H76847-103	H65415-103
SSDPECME040T401	943188	H76848-102	H65417-102	H76848-103	H65417-103
SSDPECME016T410	943189	H76849-102	H65413-102	H76849-103	H65413-103
SSDPECME032T410	943190	H76850-102	H65415-102	H76850-103	H65415-103
SSDPECME040T410	943191	H76851-102	H65417-102	H76851-103	H65417-103

PCN Revision History:

Date of Revision:

December 8, 2015

Revision Number:

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Reason:

Originally Published PCN



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

Asia Pacific/PRC Contact: apacgccb@intel.com

Europe Email: eccb@intel.com

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